



Size: **52 x 52 mm**
 Thickness: **1,6 mm**
 Weight: **10 g**
 Electricity Line: **Copper**
 Thickness of copper: **35um**
 Thickness of the dielectric: **70um**
 Thickness of the aluminum-base: **1.5mm**

Lenses for PCB 724-151:



4 B ST 13060 XP



4 B 3570 D

The result of the test:

| Item | Test item | Technology request | Unit | Test result | |
|------|---|------------------------------|---------------------|-------------------|-------------------|
| 1 | Peel Strength | A | ≥1.8 | N/mm | 2.0 |
| | After thermal stress (260°C) | ≥1.8 | N/mm | 1.8 | |
| 2 | Blister test After Thermal stress (288°C , 2min) | 288°C, 2 min No delaminating | / | Ok | |
| 3 | Thermal resistance | ≤2.0 | °C/W | 1.0 | |
| 4 | Thermal-Conductive Factor | | W/m-k | 1.0 | |
| 5 | Flammability(A) | FV-O | / | FV-O | |
| 6 | Surface Resistivity | A | ≥ 1×10 ⁵ | MΩ | 5×10 ⁷ |
| | Constant humidity treatment (90%,35°C,96h) | ≥ 1×10 ⁵ | MΩ | 2×10 ⁶ | |
| 7 | Volume Resistivity | A | ≥ 1×10 ⁶ | MΩ·m | 4×10 ⁸ |
| | Constant humidity treatment (90%,35°C,96h) | ≥ 1×10 ⁶ | MΩ·m | 5×10 ⁷ | |
| 8 | Dielectric Breakdown(DC) | ≥ 28.5 | KV/MM | 31 | |
| 9 | Dielectric constant(1MHz) (40°C, 93%, 96h) | ≤4.4 | / | 4.2 | |
| 10 | Dielectric dissipation factor (1MHz) (40°C , 93% , 96h) | ≤0.03 | / | 0.02 | |

